



NOW PART OF



Reliability Data Report

Product Family R572

LT4275 / LT4276 / LT4294 / LT4295 /
LT4320 / LT4321

Reliability Data Report

Report Number: R572

Report generated on: Tue Sep 25 10:28:43 PDT 2018

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C)¹	No. of FAILURES _{2, 3}
QFN/DFN	331	1304	1552	2490	0
SOIC/MSOP	40	1304	1304	79	0
Totals	371	-	-	2,569	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C)⁴	No. of FAILURES
QFN/DFN	348	1408	1441	816	0
SOIC/MSOP	120	1635	1648	230	0
Totals	468	-	-	1,046	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/MSOP	598	1320	1648	14	0
QFN/DFN	304	1410	1506	39	0
Totals	902	-	-	53	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/MSOP	600	1320	1648	60	0
QFN/DFN	303	1410	1506	208	0
Totals	903	-	-	268	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/MSOP	400	1320	1617	40	0
QFN/DFN	50	1506	1506	5	0
Totals	450	-	-	45	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.71 FITS

(3) Mean Time Between Failure in Years = 159974.45

(4) Assumes 20X Acceleration from 85 °C to +130 °C

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/MSOP	200	1635	1648	200	0
QFN/DFN	100	1410	1410	100	0
Totals	300	-	-	300	0